

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	21	257/E23.078	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:33
L2	5	257/E23.187	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:35
L3	10	257/E25.016	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:36
L4	14	257/E23.006	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:36
L5	12	257/E23.109	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:37
L6	2825	257/734	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:38
L7	1261	257/727	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:40

L8	1186	257/720	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:04
L9	2422	257/713	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:18
L10	1510	257/675	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:29
L11	98	257/178	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:37
L12	76	257/118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:44
L13	134	257/181	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:49
L14	3364	257/690	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:51
S1	3	"5,008,735".pn. or "3,280,383".pn. or "4,816,424".pn.	USPAT	OR	OFF	2007/08/31 20:01
S2	0	"560167352".pn.	JPO	OR	OFF	2007/08/31 20:01
S3	1	"56167352".pn.	JPO	OR	OFF	2007/08/31 20:01

S4	3402	(semiconductor or die or dice or chip or IC) with IGBT	USPAT	OR	ON	2008/03/24 14:35
S5	18	(semiconductor or die or dice or chip or IC) with IGBT and multi near (films or layers) with (connector or solder or contact)	USPAT	OR	ON	2008/03/24 14:37
S6	257	(semiconductor or die or dice or chip or IC) with IGBT with (connector or solder or contact)	USPAT	OR	ON	2008/03/24 14:42
S7	0	(semiconductor or die or dice or chip or IC) with IGBT same (connector or solder or contact) near lamina	USPAT	OR	ON	2008/03/24 14:42
S8	0	(semiconductor or die or dice or chip or IC) with IGBT and (connector or solder or contact) near lamina	USPAT	OR	ON	2008/03/24 14:42
S9	1	(semiconductor or die or dice or chip or IC) with IGBT and (connector or solder or contact) with lamina	USPAT	OR	ON	2008/03/24 14:43
S10	8	("4478787" "4999336" "5004498" "5292478").PN. OR ("6579623").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 15:19
S11	543	(semiconductor or die or dice or chip or IC) with IGBT same (connector or solder or contact)	USPAT	OR	ON	2008/03/24 15:37
S12	37	(semiconductor or die or dice or chip or IC) with IGBT and multi near (films or layers) same (connector or solder or contact)	USPAT	OR	ON	2008/03/24 15:38
S13	19	S12 not S5	USPAT	OR	ON	2008/03/24 15:38

S14	544	(semiconductor or die or dice or chip or IC) with IGBT and (connector or solder or contact) with (coat\$3 or plat\$3)	USPAT	OR	ON	2008/03/24 15:40
S15	15	("4587550" "4918514" "5089439" "5360985" "5866944" "6166402" "6281569").PN. OR ("6495924").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 16:15
S16	23	("3825064" "4141030" "4426659" "4587550" "5106540" "5120665" "5399432" "5527604" "5543363" "5561321" "5695872" "5708299" "5781412" "6181007").PN. OR ("6380622").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 16:55
S17	1	"6703707".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:00
S18	11	("20030011054" "20030178719" "5594282" "6204554" "6215176" "6486554" "6590281" "6597059").PN. OR ("6917103").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:06
S19	1	"20060087023"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:11
S20	286	S11 not S6	USPAT	OR	ON	2008/03/24 17:13
S21	7	("20030022464" "5471366" "5786635" "6208156" "6773963" "6791181").PN. OR ("7215020").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:18

S22	11	("20040066630" "20050030717" "4178630" "5150274" "5276586" "5291064" "5349237" "5696405" "6600651" "6992382" "7019395").PN. OR ("7205653").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:18
S23	27	("20030071348" "20030106924" "20030132530" "3648121" "3818584" "4141030" "4538170" "4546374" "4558345" "4646129" "4685987" "4827082" "4984061" "5229646" "5248853" "5311060" "5481137" "5641997" "5708299" "5789820" "5801445" "5886400" "6072240" "6542365" "6627997").PN. OR ("6946730").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:23
S24	1365	(semiconductor or die or dice or chip or IC) with IGBT and (connector or solder or contact) with (layers or films)	USPAT	OR	ON	2008/03/24 17:38
S25	979	S24 not S11	USPAT	OR	ON	2008/03/24 17:38
S26	3	("20060270106" "5477611" "7157308").PN. OR ("7220617").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:41

S27	12	("20040061163" "20040061221" "20040222528" "20040245519" "20050082668" "20050121784" "5198685" "5426263" "6137165" "6392290" "6529380").PN. OR ("7045884").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:43
S28	2	("4560421" "5027180").PN. OR ("7045831").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:48

3/ 25/ 08 2:56:34 PM

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